

16 April 2003

10/008,665

L Number	Hits	Search Text	DB	Time stamp
-	6	5156729.pn. 4108739.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 09:03
-	23	205/102,104,157,170,176,182.ccls. and ((single or one) adj bath)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 09:11
-	5	("3770571" "4487654" "4652348" "5052103" "5320719").PN.	USPAT	2003/04/16 09:10
-	203	205/102,104,157,170,176,182.ccls. and (lamine or laminated or laminar or multilayered or multilayer or modulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 09:13
-	114	205/102,104,157,170,176,182.ccls. and (multilayered or multilayer or modulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 09:29
-	1	205/102,104,157,170,176,182.ccls. and ((compositional or structural) adj modulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 09:39
-	1543	205/102,104,157,170,176,182.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 10:49
-	35	205/102,104,157,170,176,182.ccls. and (semiconductor and (printed adj (circuit or wiring) adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 10:56
-	0	419881.apn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 10:51
-	4	"6309528"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 10:53
-	3	205/\$.ccls. and taylor.in. and inman.in. and sun.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 10:53
-	15	205/102,104,157,170,176,182.ccls. and (semiconductor with (printed adj (circuit or wiring) adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 11:04
-	344	205/157.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 11:25

-	1341	205/157,170,176,182.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 11:27
-	113	205/157,170,176,182.ccls. and (multilayer or multilayered or (multiple adj layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 11:28
-	39	(205/157,170,176,182.ccls. and (multilayer or multilayered or (multiple adj layer))) and tin	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 11:51
-	3	((205/157,170,176,182.ccls. and (multilayer or multilayered or (multiple adj layer))) and tin) and friction	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 11:52
-	71	205/157,170,176,182.ccls. and (multichip or "multi chip" or capacitor or resistor)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 12:58
-	53	205/157,170,176,182.ccls. and ((multichip or "multi chip" or capacitor or resistor) and (printed or semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 12:58
-	24	205/157,170,176,182.ccls. and ((multichip or "multi chip" or capacitor or resistor) with (printed or semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 12:58

L Number	Hits	Search Text	DB	Time stamp
37	1412	205/238,239,240,241,242,252,261,263,265,271,281,291,300,305.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 14:03
38	125	205/238,239,240,241,242,252,261,263,265,271,281,291,300,305.ccls. and (((wiring or circuit) adj board) or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 14:03
39	22	(205/238,239,240,241,242,252,261,263,265,271,281,291,300,305.ccls. and (((wiring or circuit) adj board) or semiconductor)) and (((multiple or multi) adj layer) or multilayer or	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 14:04
40	1	((205/238,239,240,241,242,252,261,263,265,271,281,291,300,305.ccls. and (((wiring or circuit) adj board) or semiconductor)) and (((multiple or multi) adj layer) or multilayer or	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 14:05
41	3	((205/238,239,240,241,242,252,261,263,265,271,281,291,300,305.ccls. and (((wiring or circuit) adj board) or semiconductor)) and (((multiple or multi) adj layer) or multilayer or multilayered)) and (pulse or pulsed or modulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 14:05
42	412	205/102,104,157,170,176,182.ccls. and (semiconductor or ((wiring or circuit) adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 14:11
43	101	(205/102,104,157,170,176,182.ccls. and (semiconductor or ((wiring or circuit) adj board))) and (pulse or pulsed or modulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 14:11
44	82	((205/102,104,157,170,176,182.ccls. and (semiconductor or ((wiring or circuit) adj board))) and (pulse or pulsed or modulated)) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 14:12
45	32	((205/102,104,157,170,176,182.ccls. and (semiconductor or ((wiring or circuit) adj board))) and (pulse or pulsed or modulated)) and tin	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 14:12
46	56	((205/102,104,157,170,176,182.ccls. and (semiconductor or ((wiring or circuit) adj board))) and (pulse or pulsed or modulated)) and potential	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 14:12
47	5	((205/102,104,157,170,176,182.ccls. and (semiconductor or ((wiring or circuit) adj board))) and (pulse or pulsed or modulated)) and (reduction adj potential)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/16 14:12